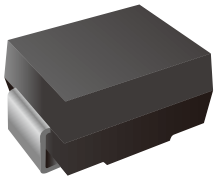
LT52B THRU LT520B

Surface Mount Schottky Barrier Rectifier

Features



- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief,ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 250°C/10 seconds at terminals
- Marking:S52~S520 or SS52~SS520

Mechanical Data

- Case: JEDEC DO-214AA. Molded plastic over glass passivated junction
- Terminal: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode except bi-directional models
- Standard Packaging: 12mm tape (EIA STD RS-481)
- Weight: 0.10g

Maximum Ratings and Electrical characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load, for capacitive load derate current by 20%.

Parameter	Symbols	LT52B	LT54B	LT56B	LT58B	LT510B	LT512B	LT515B	LT520B	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	5.0								A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	150								A
Max Instantaneous Forward Voltage at 5 A	V_F	0.55		0.70	0.85		0.95			V
Maximum DC Reverse Current at Rated DC Reverse Voltage T_a = 25°C T_a =100°C	I_R	1.0 50		0.3 25						mA
Typical Junction Capacitance (1)	C_j	500		300						pF
Typical Thermal Resistance (2)	$R_{\theta JA}$	50								°C/W
Operating Junction Temperature Range	T_j	-55 ~ +125			-55 ~ +150					°C
Storage Temperature Range	T_{stg}	-55 ~ +150								°C

(1) Measured at 1MHz and applied reverse voltage of 4 V D.C.
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Electrical characteristics Curves

Fig.1 Forward Current Derating Curve

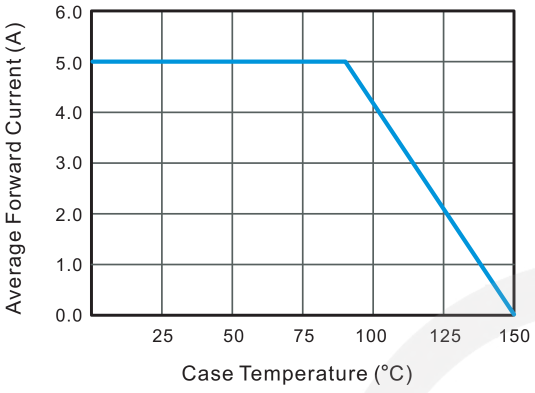


Fig.2 Typical Reverse Characteristics

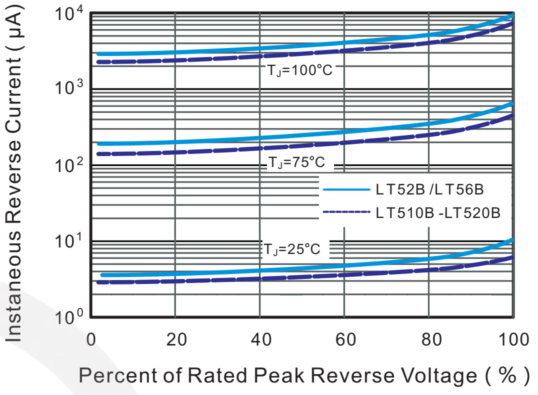


Fig.3 Typical Forward Characteristic

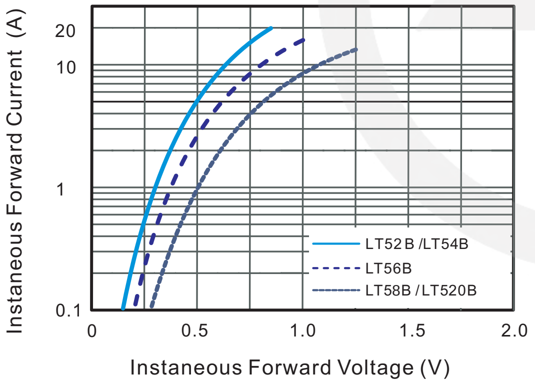


Fig.4 Typical Junction Capacitance

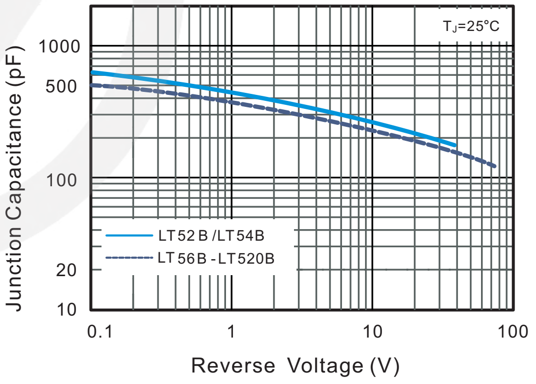


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

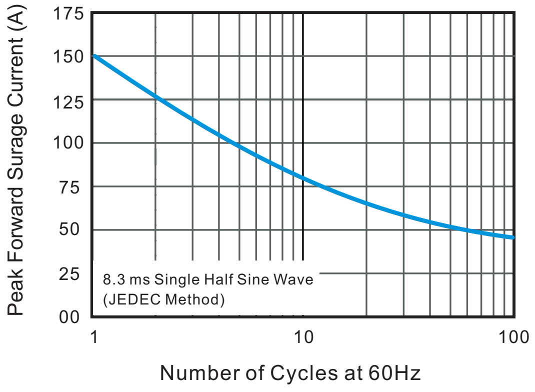
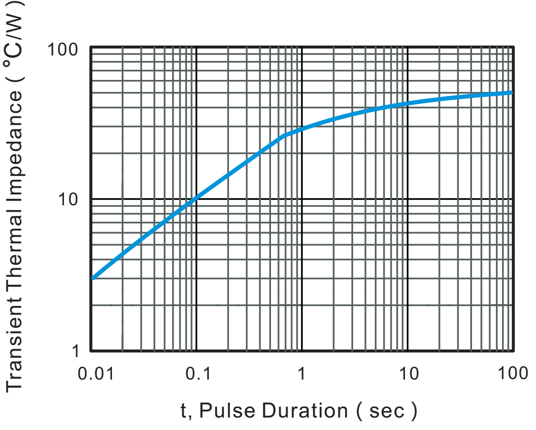
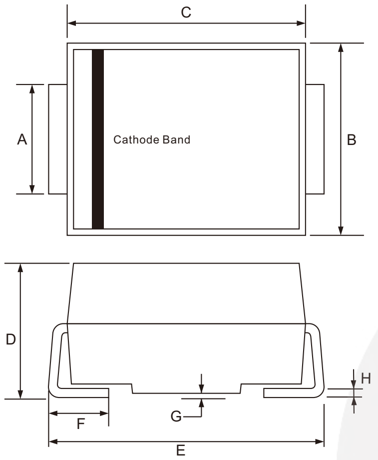


Fig.6- Typical Transient Thermal Impedance



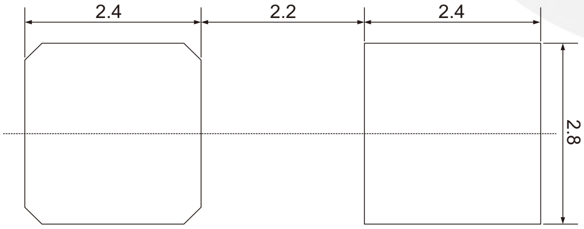
SMB Package Outline



Unit: mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.90	2.20
B	3.30	3.94
C	4.05	4.75
D	2.13	2.65
E	5.08	5.59
F	0.76	1.52
G	0.203 TYP.	
H	0.15	0.31

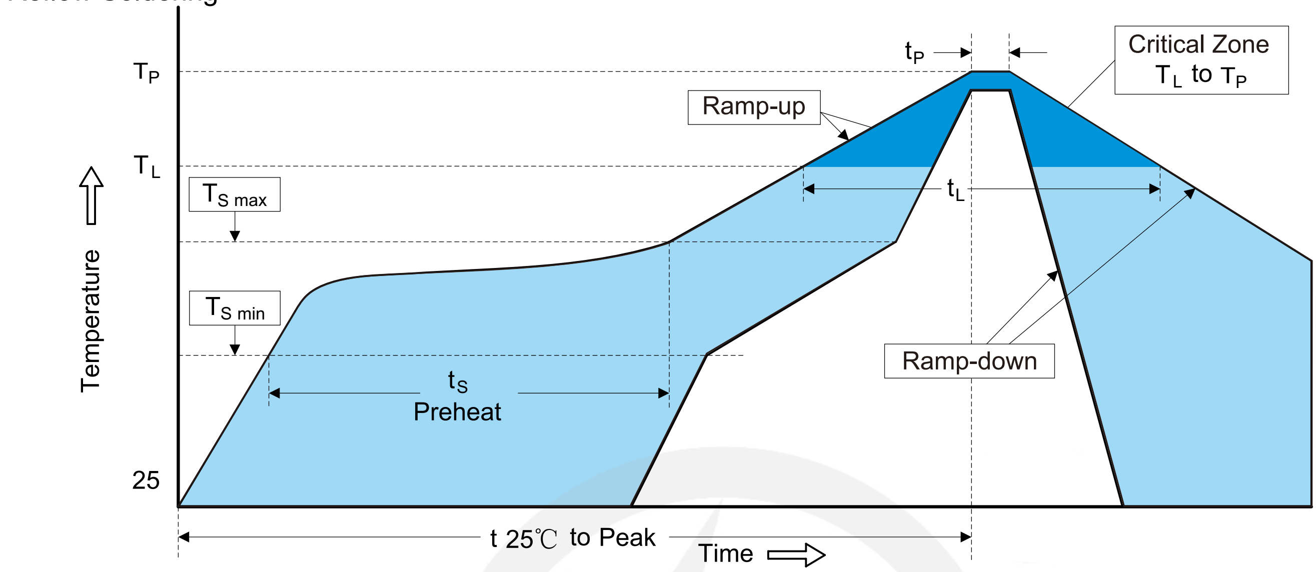
SMB Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm
3.The pad layout is for reference purpose only.

Recommended Soldering Conditions

Reflow Soldering

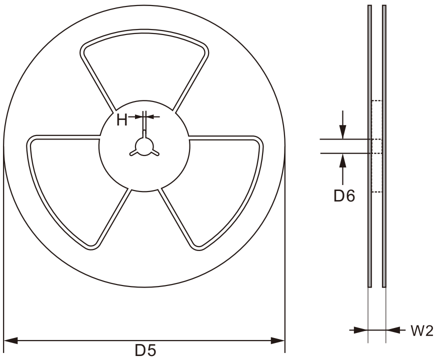


Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3℃/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_S)	150℃ 200℃ 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3℃/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217℃ 60-150 seconds
Peak Temperature (T_P)	260℃
Time within 5℃ of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max.

Packaging

13” Reel



D5	Φ330.0±2.0
D6	Φ13.5±0.5
H	2.5±1.0
W2	16.0±2.0

Quantity: 3000PCS